Amkor Technology Receives "Device of the Year" Award for SWIFT Semiconductor Package

Amkor Technology, Inc. recently received the 3D InCites "Device of the Year" award during SEMICON West for its' SWIFT™ semiconductor package. The awards were a result of industry voting for individuals, companies and products exhibiting excellence in 3D packaging expertise and contributing to the commercialization of game-changing technologies such as: fan-out wafer level packaging (FOWLP), interposer-based packages, 3D stacks and 3D System-in-Package (SiP).

Amkor's SWIFT™ product was uniquely developed to deliver a high yielding, high-performance package with the thinnest profile in the industry. This package can deliver 2 μm line/space lithography with up to 4 layers of RDL and a very dense network of memory interface vias from bottom package to the top package at a very cost competitive price. For more information on this new package visit: http://www.amkor.com/go/technology/swift

Jon Woodyard, Amkor's VP of Technical Programs accepts the 3D InCites award for "Device of the Year" from Francoise von Trapp and Stephen Hiebert, KLA-Tencor.

Join Us For These Upcoming Events

Mark your calendars and join Amkor at the following events.

09/01/16 | SMIC Technology Symposium Shanghai
09/13/16 | ESTC 2016 Conference
09/15/16 | European MEMS Summit 2016
09/22/16 | The 3rd Global Sensor Summit & China IoT Application Summit
09/22/16 | SMIC Technology Symposium Shenzhen
10/10/16 | IMAPS 2016 - Pasadena
10/12/16 | 2016 ICCAD
10/22/16 | 2016 IWLPC
11/08/16 | IC China 2016

For more information, please contact us at: sales@amkor.com

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